

CLAIMS

1. A wafer supporting device comprising:

a wafer support, disposed within a process chamber
in a semiconductor manufacturing apparatus having
5 respective heat sources in upper and lower regions thereof,
having an upper surface provided with a support area for
supporting a wafer;

aplurality of lift members, extending from the outside
of said support area of said wafer support to the inside
10 of said support area and having an upper surface provided
with an inclined surface inclining downward toward the inside,
movable vertically between respective positions above and
below said upper surface of said wafer support;

an arc-shaped lift ring, disposed outside said support
15 area, having an inner peripheral edge integrally formed with
said lift members; and

a lift pin, adapted to vertically move through a through
hole formed in said wafer support, having an upper end
connected to said lift ring;

20 wherein said through hole is covered and substantially
closed with said lift ring when said lift pin descends.

2. A wafer supporting device according to claim
1, further comprising driving means, disposed lower than
said lift pin, for vertically moving said lift pin.

25 3. A wafer supporting device according to claim
2, wherein said lift pin and said driving means are separable

from each other.

4. A wafer supporting device according to claim 1, wherein said through hole is a long hole elongated in a diametrical direction of said wafer support.

5 5. A wafer supporting device according to claim 1, wherein said lift ring has a claw member which is disposed at a position adjacent said lift member so as to be movable vertically, said claw member being adapted to be further raised while being separated from said lift ring in a state
10 where said lift ring is raised.

6. A wafer supporting device according to claim 1, wherein the upper surface of said lift member has an upward convex cross-sectional form along a circumferential direction of said support area.

15 7. A wafer supporting device according to claim 1, wherein said wafer support is rotatable.

8. A wafer supporting device according to claim 7, wherein said semiconductor manufacturing apparatus is an epitaxial growth apparatus.
20